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TITLE: 1023 I/O FC CBGA 33 X 33 PKG 1 MM PITCH LEAD FREE SPHERES			DOCUMENT NO: 98ARE10612D	REV: F	
			STANDARD: NON-JEDEC		
			SOT1601-1	17 DEC 2015	



NOTES:

1. ALL DIMENSIONS IN MILLIMETERS.
2. DIMENSIONING AND TOLERANCING PER ASME Y14.5M-1994.
3. MAXIMUM SOLDER BALL DIAMETER MEASURED PARALLEL TO DATUM A.
4. DATUM A, THE SEATING PLANE, IS DETERMINED BY THE SPHERICAL CROWNS OF THE SOLDER BALLS.
5. CAPACITORS MAY NOT BE PRESENT ON ALL DEVICES.
6. CAUTION MUST BE TAKEN NOT TO SHORT CAPACITORS OR EXPOSE METAL CAPACITOR PADS ON PACKAGE TOP.
7. ALL DIMENSIONS SYMMETRICAL ABOUT CENTERLINES UNLESS OTHERWISE SPECIFIED.

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